

SID

Factory: Rot am See

Article:

ML6

Provided:

Customer:

Date:

03.04.2026

WÜRTH
ELEKTRONIK
MORE THAN
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
---------------	----------	----	---------	------------------

A-RS Kupferfolie-035my 330x490mm	50200242	35	VS	1	
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	231		2	
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		3	
		35	L2		
B-STD-FR4-ML-0.711mm-035+035-TG150-HF...	50203135	710		4	A01
		35	L3		
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	216		5	
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		6	B00
		35	L4		
B-STD-FR4-ML-0.711mm-035+035-TG150-HF...	50203135	710		7	A02
		35	L5		
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	231		8	
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		9	
A-RS Kupferfolie-035my 330x490mm	50200242	35	RS	10	

Thickness after Pressing

B00:

2290 µm

Tol+:

240 µm

Tol-:

240 µm

Dmax:

2530 µm

Dmin:

2050 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

2400 µm

Tol+:

240 µm

Tol-:

240 µm

Dmax:

2640 µm

Dmin:

2160 µm

Measuring point: (05) over SM and galv. Cu; both sides

nominal:

2308 µm

Version 1.2.20.35

© Würth Elektronik